

Title (en)

FILLER FOR JOINT AND METHOD FOR THE PRODUCTION THEREOF

Title (de)

ZUSATZWERKSTOFF FÜR FÜGEVERBINDUNGEN UND VERFAHREN ZU DESSEN HERSTELLUNG

Title (fr)

MATERIAU D'APPORT POUR ASSEMBLAGES ET SON PROCEDE DE PRODUCTION

Publication

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Application

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Priority

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Abstract (en)

[origin: US8704136B2] The invention relates to a filler material for a thermal production of a joint or of a material layer metallically connected to the base material of or on objects of light metal and/or zinc alloys with a thermal conductivity of more than 110 W/mK, and to a method for producing the same with means for the preparation thereof in situ and/or storage. To improve the quality of the connection, it is provided according to the invention that the filler material is formed as unwindable filler wire, built up of a sheath optionally provided with a surface layer formed from polymer(s) and graphite and comprising aluminum and/or magnesium and/or zinc or a deformable alloy of these metals with a thermal conductivity of more than 110 W/mK and a core of compacted powder, whereby the core material comprises a metal powder and/or a powder of at least one metal compound and/or a non-metallic compound and/or an agent giving off gas at increased temperature and/or at least one component forming slag. The production is characterized by a filler wire production known per se, but with an optionally coated sheath of a ductile light metal or the like alloy, with a correctly positioned winding on coils and providing the same with a protection against moisture.

IPC 8 full level

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